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PBInspect: 100% non-destructive inspection of all bonded wires

With the new PBInspect system F&K Delvotec offers a complete solution for the nondestructive inspection of all bonded wires.

For the optical inspection PBInspect uses an image recognition system, to which two or more miniature cameras are connected. A programmable lighting unit with differently coloured LEDs ensures optimum lighting for each wire bond.



Camera 1 displays the wire loop, the chip surface, bond pads and bond feet. With these images previously programmed inspection tasks can be executed, e.g. whether there is any wire present, whether the wire is straight, or checking the bond foot placement on the bond pad, wire deformation and tail length.

Camera 2 measures the loop height and can even detect bond lift-offs, a new capability for optical processes.

The image recognition system is separate from the bonder's pattern recognition system and works independently. Thus it can be easily adjusted for a variety of production steps. The analysis of the stored data can be done locally or via the host computer system.

With PBInspect counter measures can be set in motion automatically when previously defined limit values are reached. From the measured data important results for the process control itself are won, e.g. in relation to different process materials or individual machines.